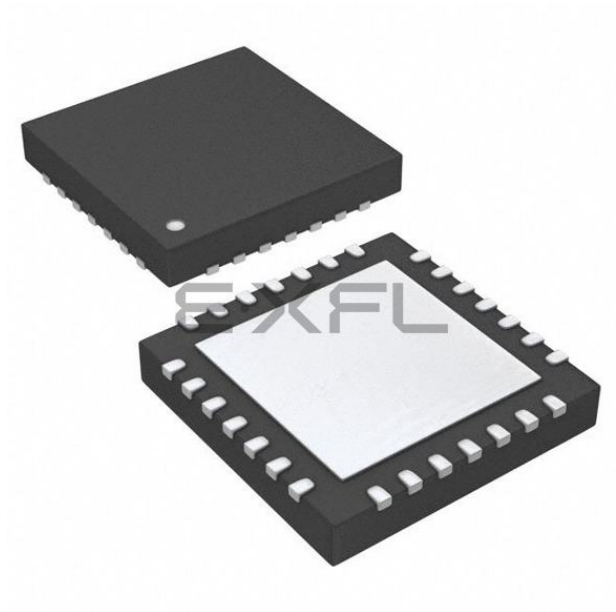


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

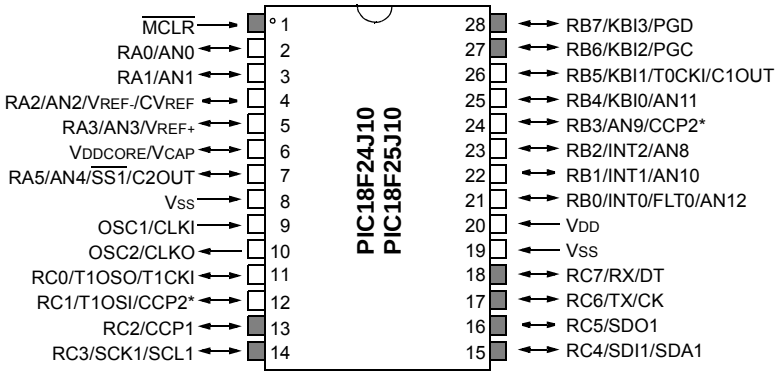
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf25j10t-i-ml

Pin Diagrams

28-Pin SPDIP, SOIC, SSOP (300 MIL)

■ = Pins are up to 5.5V tolerant

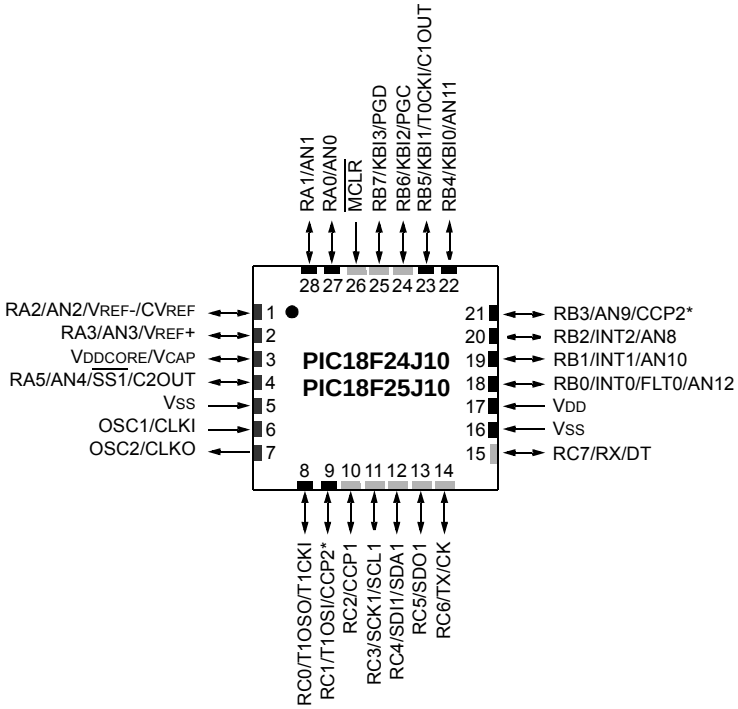


* Pin feature is dependent on device configuration.

.

28-Pin QFN

■ = Pins are up to 5.5V tolerant



* Pin feature is dependent on device configuration.

TABLE 1-2: PIC18F24J10/25J10 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number		Pin Type	Buffer Type	Description
	SPDIP, SOIC, SSOP	QFN			
					PORTA is a bidirectional I/O port.
RA0/AN0	2	27			
RA0			I/O	TTL	Digital I/O.
AN0			I	Analog	Analog Input 0.
RA1/AN1	3	28			
RA1			I/O	TTL	Digital I/O.
AN1			I	Analog	Analog Input 1.
RA2/AN2/VREF-/CVREF	4	1			
RA2			I/O	TTL	Digital I/O.
AN2			I	Analog	Analog Input 2.
VREF-			I	Analog	A/D reference voltage (low) input.
CVREF			O	Analog	Comparator reference voltage output.
RA3/AN3/VREF+	5	2			
RA3			I/O	TTL	Digital I/O.
AN3			I	Analog	Analog Input 3.
VREF+			I	Analog	A/D reference voltage (high) input.
RA5/AN4/$\overline{SS1}$/C2OUT	7	4			
RA5			I/O	TTL	Digital I/O.
AN4			I	Analog	Analog Input 4.
$\overline{SS1}$			I	TTL	SPI slave select input.
C2OUT			O	—	Comparator 2 output.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

3.0 OSCILLATOR CONFIGURATIONS

3.1 Oscillator Types

The PIC18F45J10 family of devices can be operated in five different oscillator modes:

1. HS High-Speed Crystal/Resonator
2. HSPLL High-Speed Crystal/Resonator with Software PLL Control
3. EC External Clock with FOSC/4 Output
4. ECPLL External Clock with Software PLL Control
5. INTRC Internal 31 kHz Oscillator

Four of these are selected by the user by programming the FOSC<2:0> Configuration bits. The fifth mode (INTRC) may be invoked under software control; it can also be configured as the default mode on device Resets.

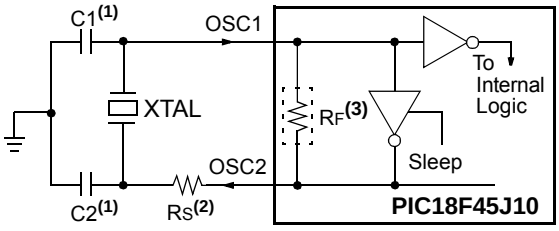
3.2 Crystal Oscillator/Ceramic Resonators (HS Modes)

In HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 3-1 shows the pin connections.

The oscillator design requires the use of a parallel cut crystal.

Note:	Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 3-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS OR HSPLL CONFIGURATION)



Note 1: See Table 3-1 and Table 3-2 for initial values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the oscillator mode chosen.

TABLE 3-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq.**	**OSC1**	**OSC2**
HS	8.0 MHz 16.0 MHz	27 pF 22 pF	27 pF 22 pF
Capacitor values are for design guidance only. These capacitors were tested with the resonators listed below for basic start-up and operation. **These values are not optimized**. Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application. See the notes following Table 3-2 for additional information.			
Resonators Used:			
4.0 MHz			
8.0 MHz			
16.0 MHz			

7.4 Erasing Flash Program Memory

The minimum erase block is 1024 bytes. Only through the use of an external programmer, or through ICSP control, can larger blocks of program memory be Bulk Erased. Word Erase in the Flash array is not supported.

When initiating an erase sequence from the micro-controller itself, a block of 1024 bytes of program memory is erased. The Most Significant 7 bits of the TBLPTR<21:10> point to the block being erased. TBLPTR<9:0> are ignored.

The EECON1 register commands the erase operation. The WREN bit must be set to enable write operations. The FREE bit is set to select an erase operation.

For protection, the write initiate sequence for EECON2 must be used.

A long write is necessary for erasing the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

7.4.1 FLASH PROGRAM MEMORY ERASE SEQUENCE

The sequence of events for erasing a block of internal program memory location is:

1. Load Table Pointer register with address of the block being erased.
2. Set the WREN and FREE bits (EECON1<2,4>) to enable the erase operation.
3. Disable interrupts.
4. Write 55h to EECON2.
5. Write 0AAh to EECON2.
6. Set the WR bit. This will begin the erase cycle.
7. The CPU will stall for duration of the erase for TIE (see parameter D133B).
8. Re-enable interrupts.

EXAMPLE 7-2: ERASING A FLASH PROGRAM MEMORY BLOCK

```
                MOVLW   CODE_ADDR_UPPER         ; load TBLPTR with the base
                MOVWF   TBLPTRU                 ; address of the memory block
                MOVLW   CODE_ADDR_HIGH
                MOVWF   TBLPTRH
                MOVLW   CODE_ADDR_LOW
                MOVWF   TBLPTRL
    ERASE_ROW
                BSF     EECON1, WREN            ; enable write to memory
                BSF     EECON1, FREE            ; enable Erase operation
                BCF     INTCON, GIE             ; disable interrupts
Required        MOVLW   55h
Sequence        MOVWF   EECON2                  ; write 55h
                MOVLW   0AAh
                MOVWF   EECON2                  ; write 0AAh
                BSF     EECON1, WR              ; start erase (CPU stall)
                BSF     INTCON, GIE             ; re-enable interrupts
```

10.3 PORTB, TRISB and LATB Registers

PORTB is an 8-bit wide, bidirectional port. The corresponding Data Direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a high-impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

The Data Latch register (LATB) is also memory mapped. Read-modify-write operations on the LATB register read and write the latched output value for PORTB.

EXAMPLE 10-3: INITIALIZING PORTB

```
CLRF   PORTB    ; Initialize PORTB by
                ; clearing output
                ; data latches
CLRF   LATB     ; Alternate method
                ; to clear output
                ; data latches
MOVLW  0Fh      ; Set RB<4:0> as
MOVWF  ADCON1   ; digital I/O pins
MOVLW  0CFh     ; Value used to
                ; initialize data
                ; direction
MOVWF  TRISB    ; Set RB<3:0> as inputs
                ; RB<5:4> as outputs
                ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit, $\overline{\text{RBPU}}$ (INTCON2<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

Note: On a Power-on Reset, RB<4:0> are configured as analog inputs by default and read as '0'; RB<7:5> are configured as digital inputs.

Four of the PORTB pins (RB<7:4>) have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB<7:4>) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are ORed together to generate the RB Port Change Interrupt with Flag bit, RBIF (INTCON<0>).

This interrupt can wake the device from Sleep mode or any of the Idle modes. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB (except with the MOVFF (ANY), PORTB instruction).
b) Clear flag bit, RBIF.

A mismatch condition will continue to set flag bit, RBIF. Reading PORTB will end the mismatch condition and allow flag bit, RBIF, to be cleared.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

RB3 can be configured by the Configuration bit, CCP2MX, as the alternate peripheral pin for the CCP2 module (CCP2MX = 0).

The RB5 pin is multiplexed with the Timer0 module clock input and one of the comparator outputs to become the RB5/KBI1/T0CKI/C1OUT pin.

14.0 CAPTURE/COMPARE/PWM (CCP) MODULES

PIC18F45J10 family devices all have two CCP (Capture/Compare/PWM) modules. Each module contains a 16-bit register which can operate as a 16-bit Capture register, a 16-bit Compare register or a PWM Master/Slave Duty Cycle register.

In 28-pin devices, the two standard CCP modules (CCP1 and CCP2) operate as described in this chapter. In 40/44-pin devices, CCP1 is implemented as an Enhanced CCP module (ECCP1) with standard Capture and Compare modes and Enhanced PWM modes. The Enhanced CCP implementation is discussed in **Section 15.0 "Enhanced Capture/Compare/PWM (ECCP) Module"**.

The Capture and Compare operations described in this chapter apply to all standard and Enhanced CCP modules.

Note: Throughout this section and **Section 15.0 "Enhanced Capture/Compare/PWM (ECCP) Module"**, references to the register and bit names for CCP modules are referred to generically by the use of 'x' or 'y' in place of the specific module number. Thus, "CCPxCON" might refer to the control register for CCP1, CCP2 or ECCP1. "CCPxCON" is used throughout these sections to refer to the module control register regardless of whether the CCP module is a standard or Enhanced implementation.

REGISTER 14-1: CCPxCON: CCP1/CCP2 CONTROL REGISTER IN 28-PIN DEVICES

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DCxB1	DCxB0	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DCxB<1:0>:** PWM Duty Cycle bit 1 and bit 0

Capture mode:
Unused.

Compare mode:
Unused.

PWM mode:
These bits are the two LSbs (bit 1 and bit 0) of the 10-bit PWM duty cycle. The eight MSbs (DCxB<9:2>) of the duty cycle are found in CCPRxL.

bit 3-0 **CCPxM<3:0>:** CCPx Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)
0001 = Reserved
0010 = Compare mode, toggle output on match (CCPxIF bit is set)
0011 = Reserved
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode: initialize CCPx pin low; on compare match, force CCPx pin high (CCPxIF bit is set)
1001 = Compare mode: initialize CCPx pin high; on compare match, force CCPx pin low (CCPxIF bit is set)
1010 = Compare mode: generate software interrupt on compare match (CCPxIF bit is set, CCPx pin reflects I/O state)
1011 = Compare mode: trigger special event, reset timer, start A/D conversion on CCPx match (CCPxIF bit is set)
11xx = PWM mode

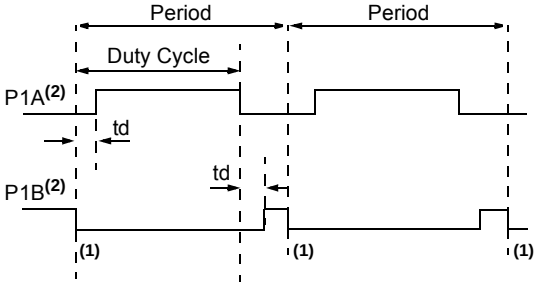
15.4.4 HALF-BRIDGE MODE

In the Half-Bridge Output mode, two pins are used as outputs to drive push-pull loads. The PWM output signal is output on the P1A pin, while the complementary PWM output signal is output on the P1B pin (Figure 15-4). This mode can be used for half-bridge applications, as shown in Figure 15-5, or for full-bridge applications where four power switches are being modulated with two PWM signals.

In Half-Bridge Output mode, the programmable dead-band delay can be used to prevent shoot-through current in half-bridge power devices. The value of bits, PDC<6:0>, sets the number of instruction cycles before the output is driven active. If the value is greater than the duty cycle, the corresponding output remains inactive during the entire cycle. See **Section 15.4.6 "Programmable Dead-Band Delay"** for more details of the dead-band delay operations.

Since the P1A and P1B outputs are multiplexed with the PORTC<2> and PORTD<5> data latches, the TRISC<2> and TRISD<5> bits must be cleared to configure P1A and P1B as outputs.

FIGURE 15-4: HALF-BRIDGE PWM OUTPUT

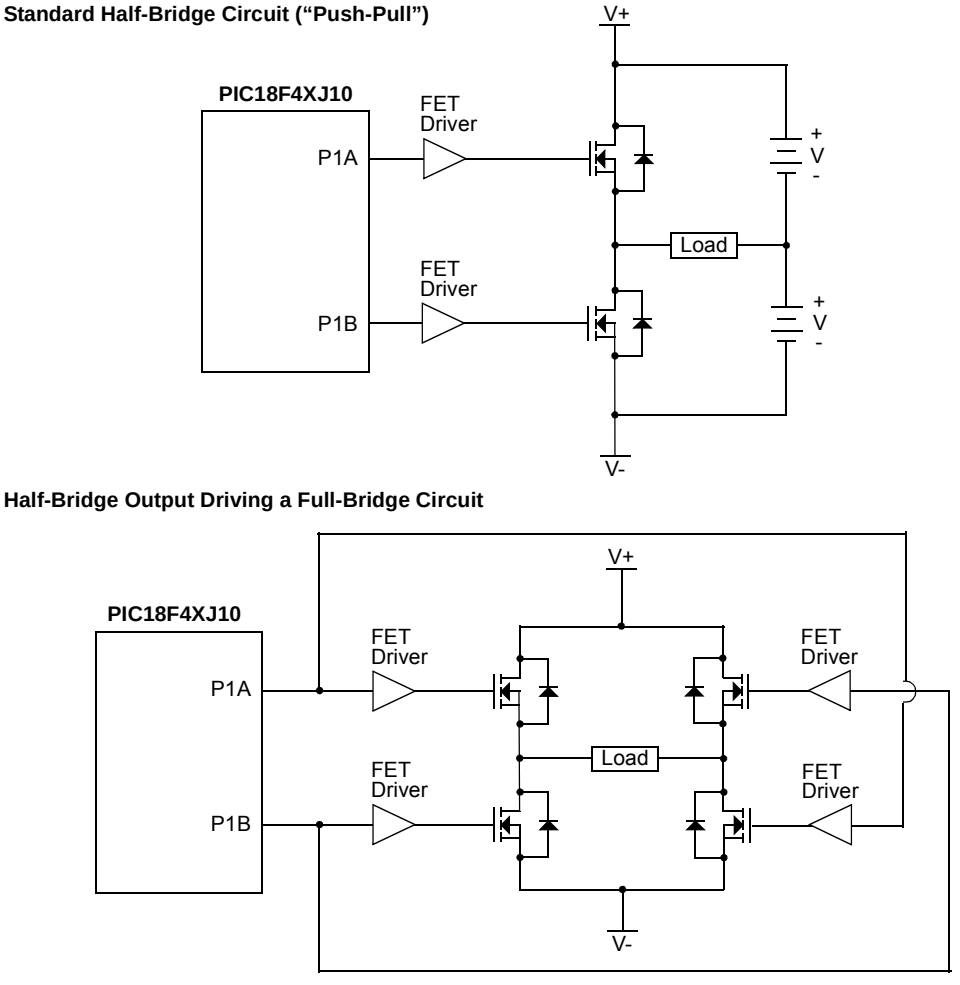


td = Dead-Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 15-5: EXAMPLES OF HALF-BRIDGE OUTPUT MODE APPLICATIONS



15.4.7.1 Auto-Shutdown and Automatic Restart

The auto-shutdown feature can be configured to allow automatic restarts of the module following a shutdown event. This is enabled by setting the PRSEN bit of the ECCP1DEL register (ECCP1DEL<7>).

In Shutdown mode with PRSEN = 1 (Figure 15-10), the ECCPASE bit will remain set for as long as the cause of the shutdown continues. When the shutdown condition clears, the ECCPASE bit is cleared. If PRSEN = 0 (Figure 15-11), once a shutdown condition occurs, the ECCPASE bit will remain set until it is cleared by firmware. Once ECCPASE is cleared, the Enhanced PWM will resume at the beginning of the next PWM period.

Note:	Writing to the ECCPASE bit is disabled while a shutdown condition is active.

Independent of the PRSEN bit setting, if the auto-shutdown source is one of the comparators, the shutdown condition is a level. The ECCPASE bit cannot be cleared as long as the cause of the shutdown persists.

The Auto-Shutdown mode can be forced by writing a '1' to the ECCPASE bit.

15.4.8 START-UP CONSIDERATIONS

When the ECCP module is used in the PWM mode, the application hardware must use the proper external pull-up and/or pull-down resistors on the PWM output pins. When the microcontroller is released from Reset, all of the I/O pins are in the high-impedance state. The external circuits must keep the power switch devices in the OFF state until the microcontroller drives the I/O pins with the proper signal levels, or activates the PWM output(s).

The CCP1M<1:0> bits (CCP1CON<1:0>) allow the user to choose whether the PWM output signals are active-high or active-low for each pair of PWM output pins (P1A/P1C and P1B/P1D). The PWM output polarities must be selected before the PWM pins are configured as outputs. Changing the polarity configuration while the PWM pins are configured as outputs is not recommended, since it may result in damage to the application circuits.

The P1A, P1B, P1C and P1D output latches may not be in the proper states when the PWM module is initialized. Enabling the PWM pins for output at the same time as the ECCP module may cause damage to the application circuit. The ECCP module must be enabled in the proper output mode and complete a full PWM cycle before configuring the PWM pins as outputs. The completion of a full PWM cycle is indicated by the TMR2IF bit being set as the second PWM period begins.

FIGURE 15-10: PWM AUTO-SHUTDOWN (PRSEN = 1, AUTO-RESTART ENABLED)

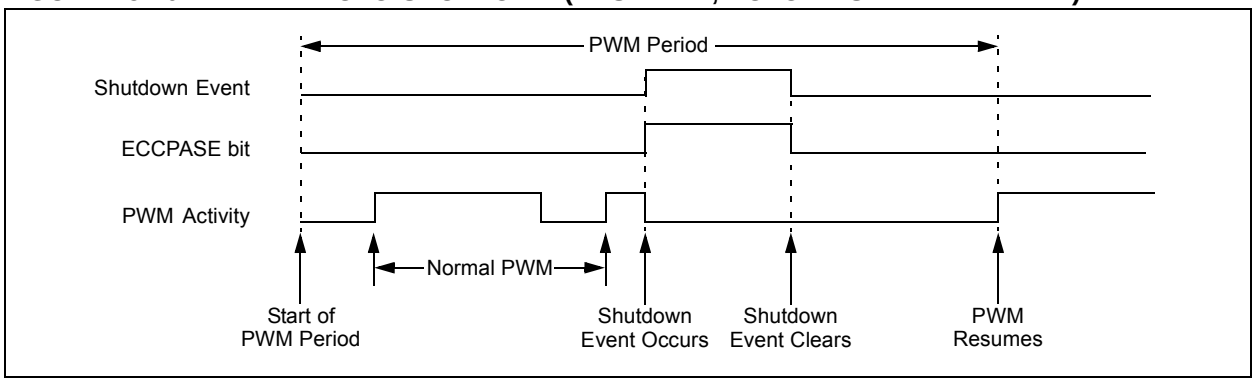


FIGURE 15-11: PWM AUTO-SHUTDOWN (PRSEN = 0, AUTO-RESTART DISABLED)

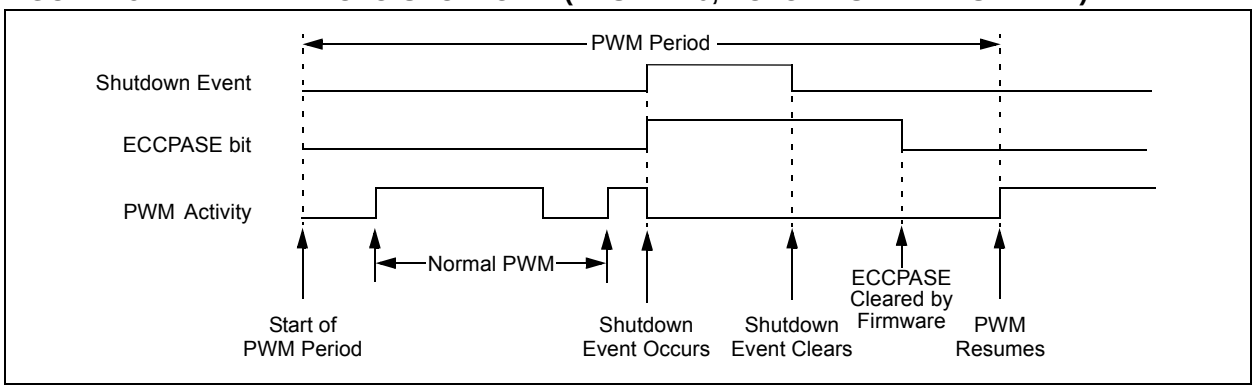
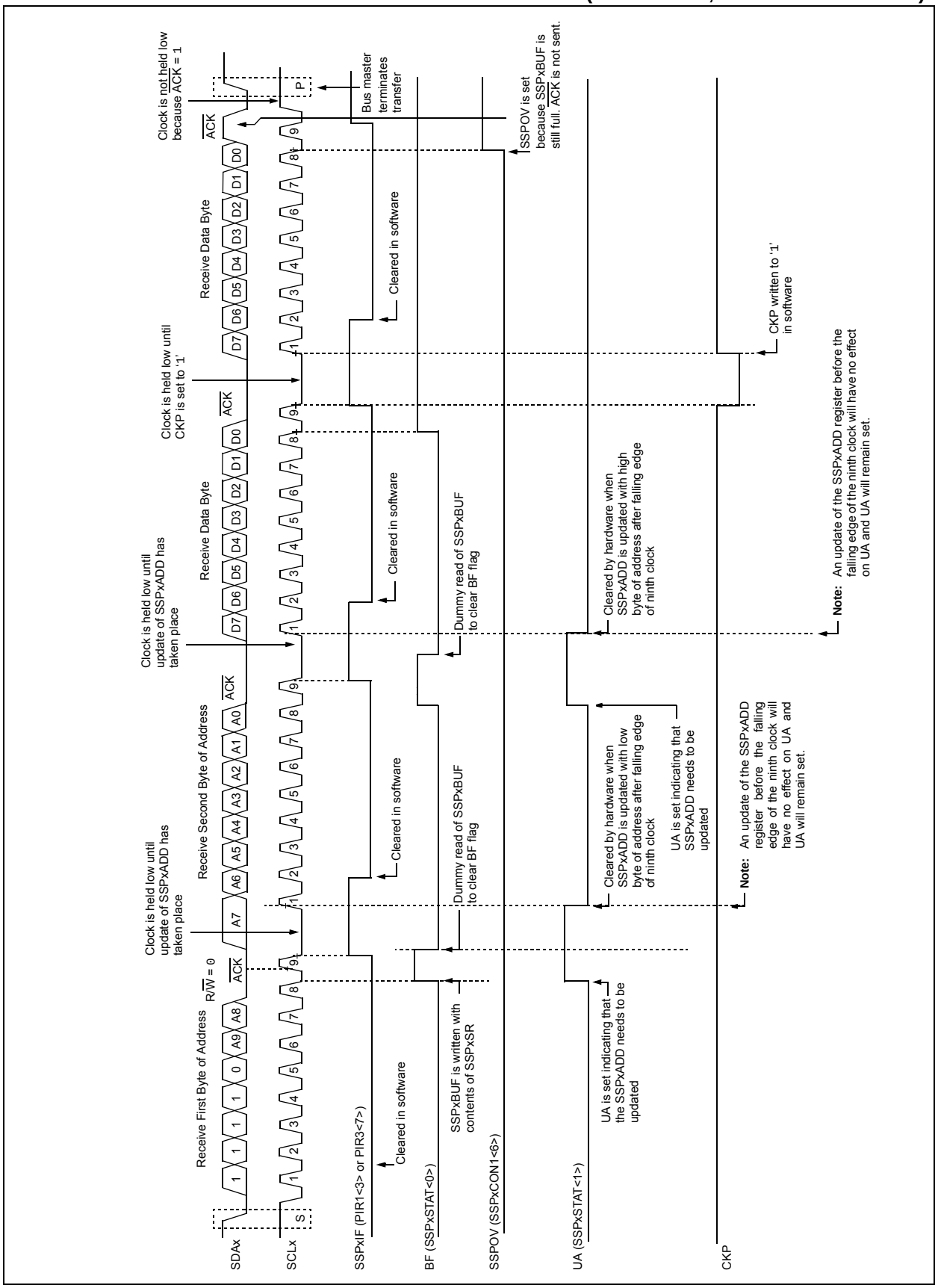


TABLE 15-3: REGISTERS ASSOCIATED WITH ECCP1 MODULE AND TIMER1

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	47
RCON	IPEN	—	$\overline{CM}$	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	46
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	49
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	49
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	49
PIR2	OSCFIF	CMIF	—	—	BCL1IF	—	—	CCP2IF	49
PIE2	OSCFIE	CMIE	—	—	BCL1IE	—	—	CCP2IE	49
IPR2	OSCFIP	CMIP	—	—	BCL1IP	—	—	CCP2IP	49
TRISB	PORTB Data Direction Control Register								50
TRISC	PORTC Data Direction Control Register								50
TRISD(1)	PORTD Data Direction Control Register								50
TMR1L	Timer1 Register Low Byte								48
TMR1H	Timer1 Register High Byte								48
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	48
TMR2	Timer2 Register								48
T2CON	—	T2OUTPS3	T2OUTPS2	T2OUTPS1	T2OUTPS0	TMR2ON	T2CKPS1	T2CKPS0	48
PR2	Timer2 Period Register								48
CCPR1L	Capture/Compare/PWM Register 1 Low Byte								49
CCPR1H	Capture/Compare/PWM Register 1 High Byte								49
CCP1CON	P1M1(1)	P1M0(1)	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	49
ECCP1AS	ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1(1)	PSSBD0(1)	49
ECCP1DEL	PRSEN	PDC6(1)	PDC5(1)	PDC4(1)	PDC3(1)	PDC2(1)	PDC1(1)	PDC0(1)	49

Legend: — = unimplemented, read as '0'. Shaded cells are not used during ECCP operation.
Note 1: These registers and/or bits are not implemented on 28-pin devices and should be read as '0'.

FIGURE 16-14: I²C™ SLAVE MODE TIMING WITH SEN = 1 (RECEPTION, 10-BIT ADDRESSING)



16.4.10 I²C MASTER MODE TRANSMISSION

Transmission of a data byte, a 7-bit address or the other half of a 10-bit address is accomplished by simply writing a value to the SSPxBUF register. This action will set the Buffer Full flag bit, BF, and allow the Baud Rate Generator to begin counting and start the next transmission. Each bit of address/data will be shifted out onto the SDAx pin after the falling edge of SCLx is asserted (see data hold time specification parameter 106). SCLx is held low for one Baud Rate Generator rollover count (TBRG). Data should be valid before SCLx is released high (see data setup time specification parameter 107). When the SCLx pin is released high, it is held that way for TBRG. The data on the SDAx pin must remain stable for that duration and some hold time after the next falling edge of SCLx. After the eighth bit is shifted out (the falling edge of the eighth clock), the BF flag is cleared and the master releases SDAx. This allows the slave device being addressed to respond with an $\overline{ACK}$ bit during the ninth bit time if an address match occurred, or if data was received properly. The status of $\overline{ACK}$ is written into the ACKDT bit on the falling edge of the ninth clock. If the master receives an Acknowledge, the Acknowledge Status bit, ACKSTAT, is cleared; if not, the bit is set. After the ninth clock, the SSPxIF bit is set and the master clock (Baud Rate Generator) is suspended until the next data byte is loaded into the SSPxBUF, leaving SCLx low and SDAx unchanged (Figure 16-21).

After the write to the SSPxBUF, each bit of the address will be shifted out on the falling edge of SCLx until all seven address bits and the R/$\overline{W}$ bit are completed. On the falling edge of the eighth clock, the master will deassert the SDAx pin, allowing the slave to respond with an Acknowledge. On the falling edge of the ninth clock, the master will sample the SDAx pin to see if the address was recognized by a slave. The status of the $\overline{ACK}$ bit is loaded into the ACKSTAT status bit (SSPxCON2<6>). Following the falling edge of the ninth clock transmission of the address, the SSPxIF is set, the BF flag is cleared and the Baud Rate Generator is turned off until another write to the SSPxBUF takes place, holding SCLx low and allowing SDAx to float.

16.4.10.1 BF Status Flag

In Transmit mode, the BF bit (SSPxSTAT<0>) is set when the CPU writes to SSPxBUF and is cleared when all 8 bits are shifted out.

16.4.10.2 WCOL Status Flag

If the user writes to the SSPxBUF when a transmit is already in progress (i.e., SSPxSR is still shifting out a data byte), the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur) after 2 TCY after the SSPxBUF write. If SSPxBUF is rewritten within 2 TCY, the WCOL bit is set and SSPxBUF is updated. This may result in a corrupted transfer.

The user should verify that the WCOL is clear after each write to SSPxBUF to ensure the transfer is correct. In all cases, WCOL must be cleared in software.

16.4.10.3 ACKSTAT Status Flag

In Transmit mode, the ACKSTAT bit (SSPxCON2<6>) is cleared when the slave has sent an Acknowledge ($\overline{ACK}$ = 0) and is set when the slave does not Acknowledge ($\overline{ACK}$ = 1). A slave sends an Acknowledge when it has recognized its address (including a general call), or when the slave has properly received its data.

16.4.11 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the Receive Enable bit, RCEN (SSPxCON2<3>).

Note:	The MSSP module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting, and on each rollover, the state of the SCLx pin changes (high-to-low/low-to-high) and data is shifted into the SSPxSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPxSR are loaded into the SSPxBUF, the BF flag bit is set, the SSPxIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCLx low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable bit, ACKEN (SSPxCON2<4>).

16.4.11.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPxBUF from SSPxSR. It is cleared when the SSPxBUF register is read.

16.4.11.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when 8 bits are received into the SSPxSR and the BF flag bit is already set from a previous reception.

16.4.11.3 WCOL Status Flag

If the user writes the SSPxBUF when a receive is already in progress (i.e., SSPxSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write doesn't occur).

16.4.17.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDAx or SCLx are sampled low at the beginning of the Start condition (Figure 16-26).

b) SCLx is sampled low before SDAx is asserted low (Figure 16-27).

During a Start condition, both the SDAx and the SCLx pins are monitored.

If the SDAx pin is already low, or the SCLx pin is already low, then all of the following occur:

- the Start condition is aborted;
- the BCLxIF flag is set; and
- the MSSP module is reset to its Idle state (Figure 16-26).

The Start condition begins with the SDAx and SCLx pins deasserted. When the SDAx pin is sampled high, the Baud Rate Generator is loaded from SSPxADD<6:0> and counts down to '0'. If the SCLx pin is sampled low while SDAx is high, a bus collision occurs, because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDAx pin is sampled low during this count, the BRG is reset and the SDAx line is asserted early (Figure 16-28). If, however, a '1' is sampled on the SDAx pin, the SDAx pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to 0. If the SCLx pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCLx pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDAx before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 16-26: BUS COLLISION DURING START CONDITION (SDAx ONLY)

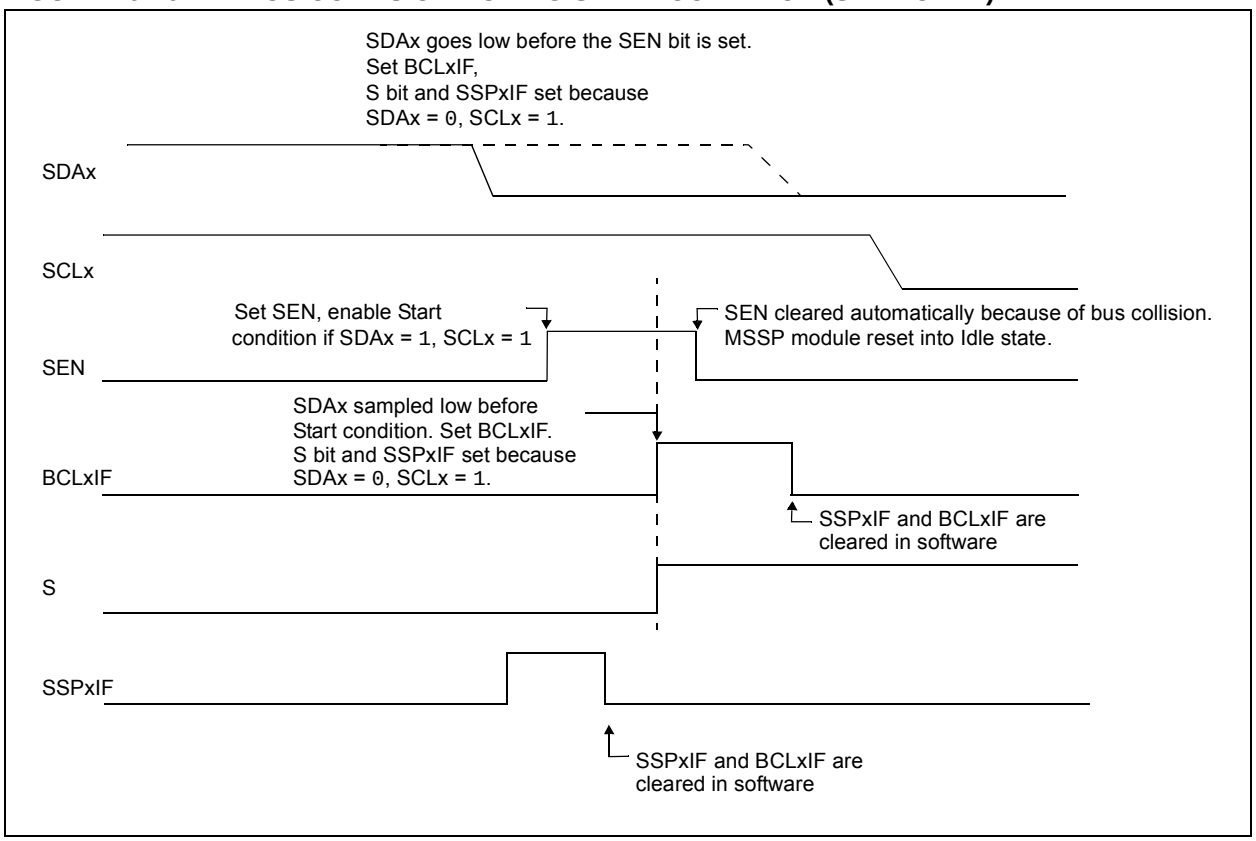


TABLE 16-4: REGISTERS ASSOCIATED WITH I²C™ OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	47
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	49
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	49
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	49
PIR2	OSCFIF	CMIF	—	—	BCL1IF	—	—	CCP2IF	49
PIE2	OSCFIE	CMIE	—	—	BCL1IE	—	—	CCP2IE	49
IPR2	OSCFIP	CMIP	—	—	BCL1IP	—	—	CCP2IP	49
PIR3	SSP2IF	BCL2IF	—	—	—	—	—	—	49
PIE3	SSP2IE	BCL2IE	—	—	—	—	—	—	49
IPR3	SSP2IP	BCL2IP	—	—	—	—	—	—	49
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	50
TRISD(1)	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	50
SSP1BUF	MSSP1 Receive Buffer/Transmit Register								48
SSP1ADD	MSSP1 Address Register (I²C™ Slave mode). MSSP1 Baud Rate Reload Register (I²C Master mode).								48
SSP1CON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	48
SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	48
	GCEN	ACKSTAT	ADMSK5(2)	ADMSK4(2)	ADMSK3(2)	ADMSK2(2)	ADMSK1(2)	SEN	48
SSP1STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	48
SSP2BUF	MSSP2 Receive Buffer/Transmit Register								50
SSP2ADD	MSSP2 Address Register (I²C Slave mode). MSSP2 Baud Rate Reload Register (I²C Master mode).								50
SSP2CON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	50
SSP2CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	50
	GCEN	ACKSTAT	ADMSK5(2)	ADMSK4(2)	ADMSK3(2)	ADMSK2(2)	ADMSK1(2)	SEN	48
SSP2STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	50

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the MSSP module in I²C™ mode.

Note 1: These registers and/or bits are not implemented on 28-pin devices and should be read as '0'.

2: Alternate names and definitions for these bits when the MSSP module is operating in I²C Slave mode. See **Section 16.4.3.2 "Address Masking"** for details.

MOVFF **Move f to f**

Syntax: MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	$ffff_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination 'f_d' can also be anywhere from 000h to FFFh.
Either source or destination can be W (a useful special situation).
MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).
The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

Words: 2

Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction
REG1 = 33h
REG2 = 11h
After Instruction
REG1 = 33h
REG2 = 33h

MOVLB **Move Literal to Low Nibble in BSR**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow BSR$

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The eight-bit literal 'k' is loaded into the Bank Select Register (BSR). The value of BSR<7:4> always remains '0', regardless of the value of k_7:k_4.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: MOVLB 5

Before Instruction
BSR Register = 02h
After Instruction
BSR Register = 05h

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – (W) – ($\overline{C}$) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	10da	ffff	ffff

Description: Subtract W and the Carry flag (borrow) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1:
```
SUBWFB  REG, 1, 0
Before Instruction
    REG  =  19h    (0001 1001)
    W    =  0Dh    (0000 1101)
    C    =  1
After Instruction
    REG  =  0Ch    (0000 1011)
    W    =  0Dh    (0000 1101)
    C    =  1
    Z    =  0
    N    =  0      ; result is positive
```

Example 2:
```
SUBWFB  REG, 0, 0
Before Instruction
    REG  =  1Bh    (0001 1011)
    W    =  1Ah    (0001 1010)
    C    =  0
After Instruction
    REG  =  1Bh    (0001 1011)
    W    =  00h
    C    =  1
    Z    =  1      ; result is zero
    N    =  0
```

Example 3:
```
SUBWFB  REG, 1, 0
Before Instruction
    REG  =  03h    (0000 0011)
    W    =  0Eh    (0000 1101)
    C    =  1
After Instruction
    REG  =  F5h    (1111 0100)
                   ; [2's comp]
    W    =  0Eh    (0000 1101)
    C    =  0
    Z    =  0
    N    =  1      ; result is negative
```

SWAPF **Swap f**

Syntax: SWAPF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<3:0>) → dest<7:4>,
(f<7:4>) → dest<3:0>

Status Affected: None

Encoding:

0011	10da	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example:
```
SWAPF   REG, 1, 0
Before Instruction
    REG  =  53h
After Instruction
    REG  =  35h
```

22.2.5 SPECIAL CONSIDERATIONS WITH MICROCHIP MPLAB® IDE TOOLS

The latest versions of Microchip's software tools have been designed to fully support the extended instruction set of the PIC18F45J10 family of devices. This includes the MPLAB C18 C compiler, MPASM assembly language and MPLAB Integrated Development Environment (IDE).

When selecting a target device for software development, MPLAB IDE will automatically set default Configuration bits for that device. The default setting for the XINST Configuration bit is '0', disabling the extended instruction set and Indexed Literal Offset Addressing mode. For proper execution of applications developed to take advantage of the extended instruction set, XINST must be set during programming.

To develop software for the extended instruction set, the user must enable support for the instructions and the Indexed Addressing mode in their language tool(s). Depending on the environment being used, this may be done in several ways:

- A menu option, or dialog box within the environment, that allows the user to configure the language tool and its settings for the project
- A command line option
- A directive in the source code

These options vary between different compilers, assemblers and development environments. Users are encouraged to review the documentation accompanying their development systems for the appropriate information.

23.7 MPLAB ICE 2000 High-Performance In-Circuit Emulator

The MPLAB ICE 2000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers. Software control of the MPLAB ICE 2000 In-Circuit Emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The architecture of the MPLAB ICE 2000 In-Circuit Emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE 2000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft® Windows® 32-bit operating system were chosen to best make these features available in a simple, unified application.

23.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The MPLAB REAL ICE probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with the popular MPLAB ICD 2 system (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

MPLAB REAL ICE is field upgradeable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added, such as software breakpoints and assembly code trace. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, real-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

23.9 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low-cost, run-time development tool, connecting to the host PC via an RS-232 or high-speed USB interface. This tool is based on the Flash PIC MCUs and can be used to develop for these and other PIC MCUs and dsPIC DSCs. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the Flash devices. This feature, along with Microchip's In-Circuit Serial Programming™ (ICSP™) protocol, offers cost-effective, in-circuit Flash debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single stepping and watching variables, and CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real time. MPLAB ICD 2 also serves as a development programmer for selected PIC devices.

23.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an SD/MMC card for file storage and secure data applications.

24.3 DC Characteristics: PIC18F45J10 Family (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**				
		All I/O Ports:				
D030		with TTL Buffer	VSS	0.15 VDD	V	VDD < 3.3V
D030A			—	0.8	V	3.3V ≤ VDD ≤ 3.6V
D031		with Schmitt Trigger Buffer	VSS	0.2 VDD	V	
D032		$\overline{MCLR}$	VSS	0.2 VDD	V	
D033		OSC1	VSS	0.3 VDD	V	HS, HSPLL modes
D033A		OSC1	VSS	0.2 VDD	V	EC, ECPLL modes(1)
D034		T1CKI	VSS	0.3	V	
	VIH	**Input High Voltage**				
		I/O Ports with non 5.5V Tolerance:(4)				
D040		with TTL Buffer	0.25 VDD + 0.8V	VDD	V	VDD < 3.3V
D040A			2.0	VDD	V	3.3V ≤ VDD ≤ 3.6V
D041		with Schmitt Trigger Buffer	0.8 VDD	VDD	V	
		I/O Ports with 5.5V Tolerance:(4)				
Dxxx		with TTL Buffer	0.25 VDD + 0.8V	5.5	V	VDD < 3.3V
DxxxA			2.0	5.5	V	3.3V ≤ VDD ≤ 3.6V
Dxxx		with Schmitt Trigger Buffer	0.8 VDD	5.5	V	
D042		$\overline{MCLR}$	0.8 VDD	VDD	V	
D043		OSC1	0.7 VDD	VDD	V	HS, HSPLL modes
D043A		OSC1	0.8 VDD	VDD	V	EC, ECPLL modes
D044		T1CKI	1.6	VDD	V	
	IIL	**Input Leakage Current(2,3)**				
D060		I/O Ports with non 5.5V Tolerance(4)	—	±0.2	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
D060A		I/O Ports with 5.5V Tolerance(4)	—	±0.2	µA	VSS ≤ VPIN ≤ 5.5V, Pin at high-impedance
D061		$\overline{MCLR}$	—	±0.2	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	±0.2	µA	Vss ≤ VPIN ≤ VDD
	IPU	**Weak Pull-up Current**				
D070	IPURB	PORTB Weak Pull-up Current	30	240	µA	VDD = 3.3V, VPIN = VSS

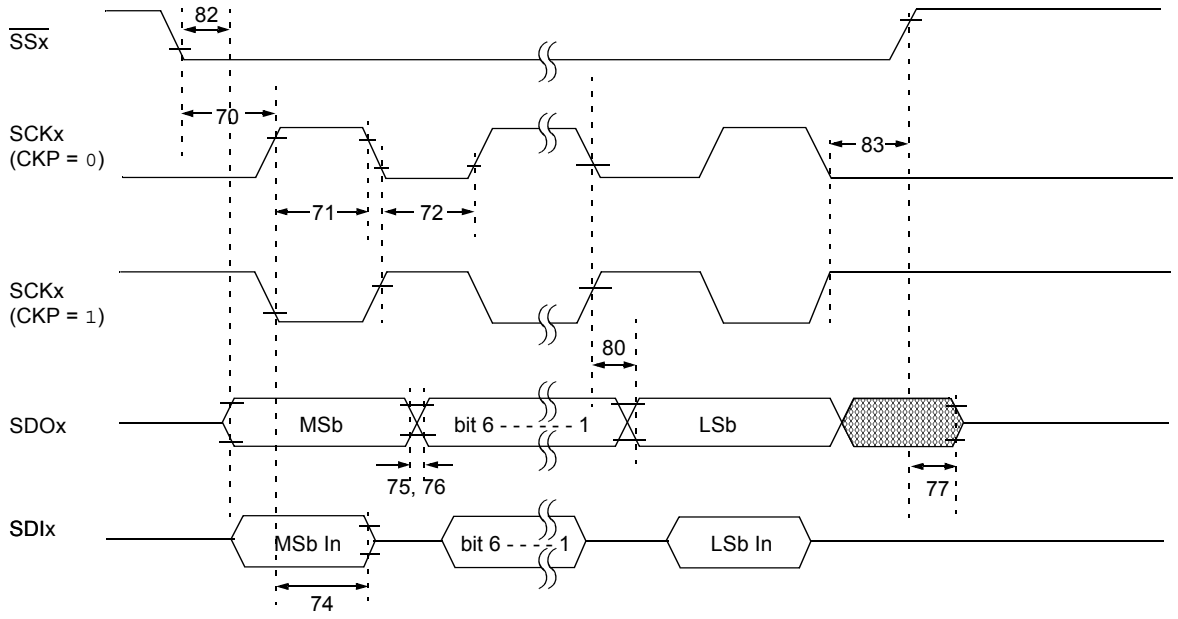
Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 10-2 for the pins that have corresponding tolerance limits.

FIGURE 24-13: EXAMPLE SPI™ SLAVE MODE TIMING (CKE = 1)



Note: Refer to Figure 24-3 for load conditions.

TABLE 24-17: EXAMPLE SPI™ SLAVE MODE REQUIREMENTS (CKE = 1)

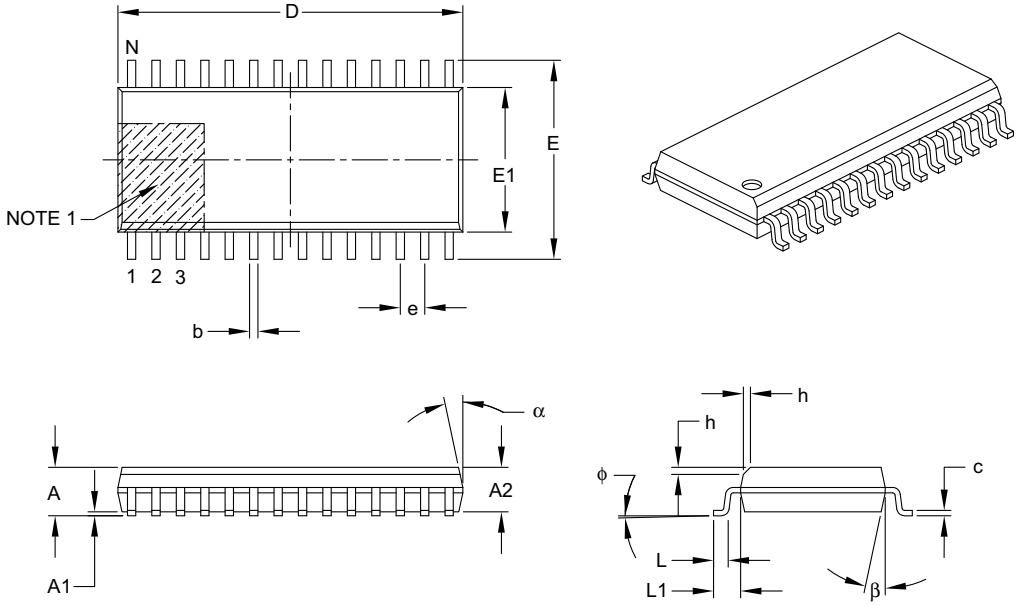
Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input		Tcy	—	ns	
71	TscH	SCKx Input High Time (Slave mode)	Continuous	1.25 Tcy + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCKx Input Low Time (Slave mode)	Continuous	1.25 Tcy + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73A	Tb2b	Last Clock Edge of Byte 1 to the First Clock Edge of Byte 2		1.5 Tcy + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge		20	—	ns	
75	TdoR	SDOx Data Output Rise Time		—	25	ns	
76	TdoF	SDOx Data Output Fall Time		—	25	ns	
77	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance		10	50	ns	
80	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge		—	50	ns	
82	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ ↓ Edge		—	50	ns	
83	TscH2ssH, TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge		1.5 Tcy + 40	—	ns	

Note 1: Requires the use of Parameter #73A.

2: Only if Parameter #71A and #72A are used.

28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	2.65
Molded Package Thickness	A2	2.05	–	–
Standoff §	A1	0.10	–	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (optional)	h	0.25	–	0.75
Foot Length	L	0.40	–	1.27
Footprint	L1		1.40 REF	
Foot Angle Top	ϕ	0°	–	8°
Lead Thickness	c	0.18	–	0.33
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B